

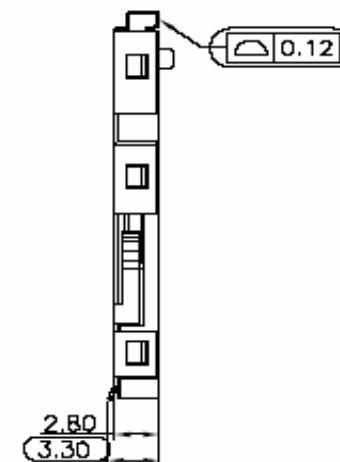
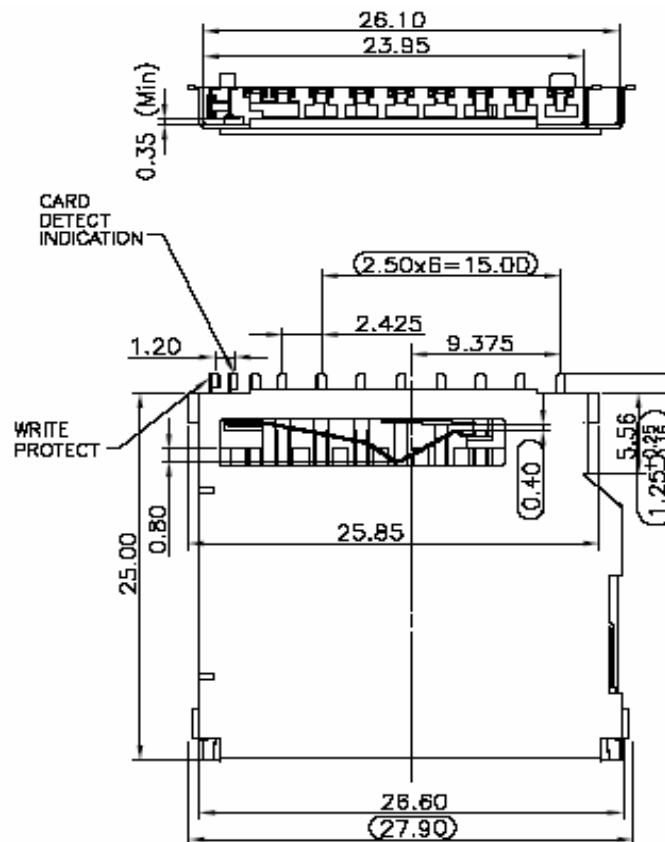
# EDCON-COMPONENTS



## Technical Description

Insulator: Thermal Plastic UL94V-0  
 Contacts: Copper Alloy  
 Boardlock: Copper Alloy  
 Contact Plating Area: 3μ AU or Select.  
                                   1μ AU Select.  
 Solder Tails Area: 100μ Tin/Lead Free  
                                   Mate Tin  
 Contact Number: 9Pin  
 Electrical  
 Current Rating: 1A max.  
 Contact Resistance: 100mΩ max.  
 Insulation Resistance: 1000MΩ Min 500VDC  
 Mechanical:  
 Lifetime: 10000 Cycles.  
 Temperature Range: - 25°C to +85°C

- 1 CD/DAT3
- 2 CMD
- 3 VSS1
- 4 VDD
- 5 CLK
- 6 VSS2
- 7 DAT0
- 8 DAT1
- 9 DAT2



TOP Mount

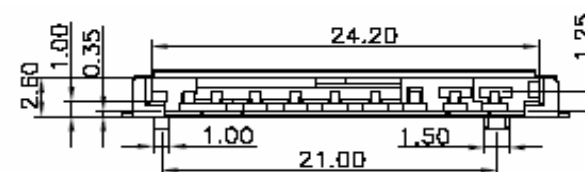
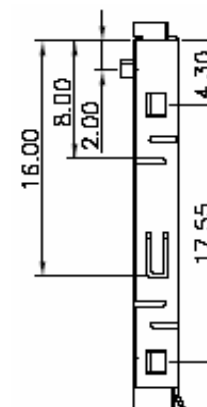
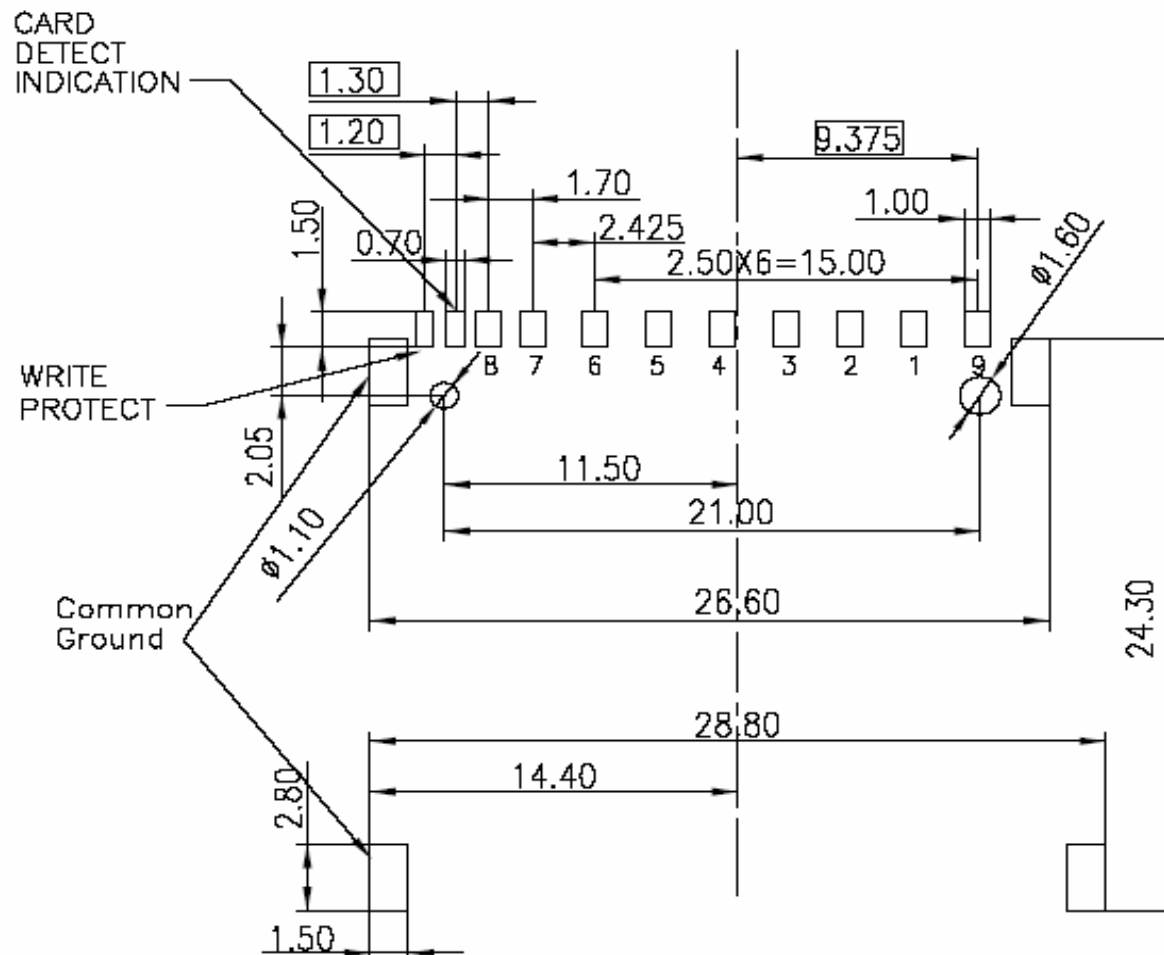
<b>SD-CARD Connector</b>	
Part No.:	<b>T58008</b>
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.11.2010
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 4	

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## PCB Layout



<b>SD-CARD Connector</b>	
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**Ordering Informations**

Serie	Contact Plating	ROHS	Packing							
<b>T58008</b>	<b>A</b>	<b>R</b>	<b>TY</b>							

<b>A</b> = 10µ Gold Plating	<b>R</b> = ROHS Conform	<b>TY</b> = Tray Packing
<b>B</b> = 3µ Gold Plating	<b>N</b> = Non ROHS Conform	

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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



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